

IN THE  
UNITED STATES PATENT AND TRADEMARK OFFICE

Inv ntor(s): Melissa D. Boyd et al.

Confirmation No.:

Application No.: Unknown

Examiner:

Filing Date: Herewith

Group Art Unit:

Title: MULTILAYERED CERAMIC SUBSTRATE SERVING AS INK MANIFOLD AND ELECTRICAL INTERCONNECTION PLATFORM FOR MULTIPLE PRINTHEAD DIES

Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

This Information Disclosure Statement is submitted:

- (X) under 37 CFR 1.97(b), or  
(Within three months of filing national application; or date of entry of national application; or before mailing date of first office action on the merits; whichever occurs last)
- ( ) under 37 CFR 1.97(c) together with either a:  
( ) Statement under 37 CFR 1.97(e), or  
( ) a \$180.00 fee under 37 CFR 1.17(p), or  
(After the CFR 1.97 (b) time period, but before final action or notice of allowance, whichever occurs first)
- ( ) under 37 CFR 1.97 (d) together with a:  
( ) Statement under 37 CFR 1.97(e)(1) or (2), and  
( ) a \$180.00 fee set forth in 37 CFR 1.17(p).  
(Filed after final action, a notice of allowance, on or before payment of the issue fee)

Please charge to Deposit Account **08-2025** the sum of \$0.00 . At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account **08-2025** pursuant to 37 CFR 1.25.

(X) Applicant(s) submit herewith Form PTO 1449 - Information Disclosure Statement together with any required copies of patents, publications or other information of which applicant(s) are aware, which applicant(s) believe(s) may be material to the examination of this application and for which there may be a duty to disclose in accordance with 37 CFR 1.56.

( ) A concise explanation of the relevance of foreign language patents, foreign language publications and other foreign language information listed on PTO Form 1449, as presently understood by the individuals(s) designated in 37 CFR 1.56 (c) most knowledgeable about the content is given on the attached sheet, or where a foreign language patent is cited in a search report or other action by a foreign patent office in a counterpart foreign application, an English language version of the search report or action which indicates the degree of relevance found by the foreign office is listed on form PTO 1449 and is enclosed herewith.

It is requested that the information disclosed herein be made of record in this application.

\*Express Mail\* label no. EV310988437US

Date of Deposit Nov. 26, 2003

I hereby certify that this is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to: Commissioner for Patents, Alexandria, VA 22313-1450.

By

Typed Name: Cyrssy Small

Respectfully submitted,

Melissa D. Boyd et al.

By

Sc tt A. Lund

Attorney/Agent for Applicant(s)  
Reg. No. 41,166

Date: N v. 26, 2003

**PATENT APPLICATION**

Sheet 1 of 2

<b>FORM PTO-1449</b>  <b>LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT</b>  (Use several sheets if necessary)	ATTY. DOCKET NO. <b>10970792-4</b>	APPLICATION NO.	CONFIRMATION NO.
	APPLICANT <b>Melissa D. Boyd et al.</b>		
	FILING DATE <b>H rewith</b>	GROUP <b>unkn.</b>	

**REFERENCE DESIGNATION U.S. PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
	1A	4,917,286	04/1990	Pollacek	
	1B	5,016,023	05/1991	Chan et al.	
	1C	5,489,930	02/1996	Anderson	
	1D	5,808,635	09/1998	Kneezel et al.	
	1E	5,939,206	08/1999	Kneezel et al.	
	1F	6,123,410	09/2000	Beerling et al.	
	1G	6,322,206	11/2001	Boyd et al.	
	1H	5,565,900	10/1996	Cowger et al.	
	1I	6,343,857	02/2002	Cowger	
	1J	4,380,770	04/1983	Maruyama	
	1K	5,087,930	02/1992	Roy et al.	

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	PUBLICATION DATE	NAME OF PATENTEE OR APPLICANT	Pages/Columns/Lines Where Relevant Passages/Figures Appear	Check if Translation attached
	1L					
	1M					
	1N					
	1O					
	1P					

**OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)**

1Q	"Precision Flip-Chip Solder Bump Interconnects For Optical Packaging"; William R. Imler et al.; December 1992; IEEE; Vol. 15; No. 6; pgs: 977-982.
1R	"Use Of AuSn Solder Bumps In Three-Dimensional Passive Aligned Packaging of LD/PD Arrays On Si Optical Benches"; Masataka Itoh, et al; 1996; IEEE; pgs: 1-7.
1S	"Active Atmosphere Solder Self-Alignment And Bonding Of Opitcal Components"; R.D. Eshmukh et al.; Vol. 16; No. 2; Second Quarter 1993; International Journal Of Microcircuits And Electronics Packaging; pgs: 97-107.

EXAMINER	DATE CONSIDERED
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**PATENT APPLICATION**

Sheet 2 of 2

<b>FORM PTO-1449</b>  <b>LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT</b>  (Use several sheets if necessary)	ATTY. DOCKET NO. <b>10970792-4</b>	APPLICATION NO.	CONFIRMATION NO.
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**REFERENCE DESIGNATION                      U.S. PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
	2A	5,097,275	03/1992	Takita	
	2B	5,561,448	10/1996	Kaneko et al.	
	2C				
	2D				
	2E				
	2F				
	2G				
	2H				
	2I				
	2J				
	2K				

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	2L					
	2M					
	2N					
	2O					
	2P					

**OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)**

	2Q	"Multilayered Focal Plane Structures With Self-Aligning Detector Assembly"; David E. Ludwig; SPIE; Vol. 2745; 1996; pgs: 149-158.
	2R	"Experimental Results On The Self-Alignment Process Using Au/Sn Metallurgy And On The Growth Of The S-Phase During The Reflow"; Christine Kallmayer, et al; 1995; Semiconductor Technology Center, Inc-Symposium; pgs 225-237.
	2S	"Photolithography In Anisotropically Etched Grooves"; S. Linder, et al.; 1996; IEEE; pgs. 38-43.

EXAMINER	DATE CONSIDERED
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